

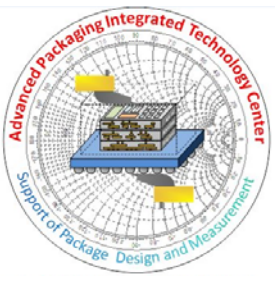
南茂科技 計畫

先進封裝材料耐電流實驗計畫



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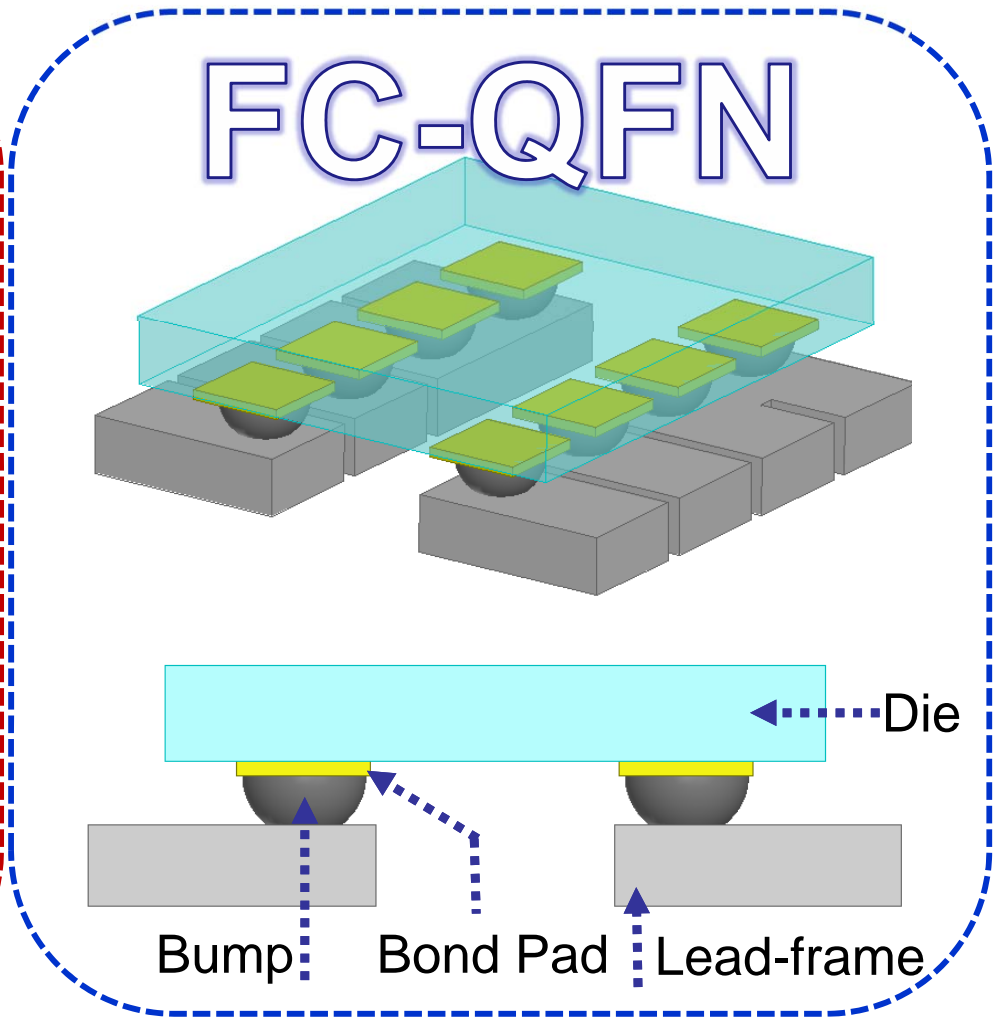
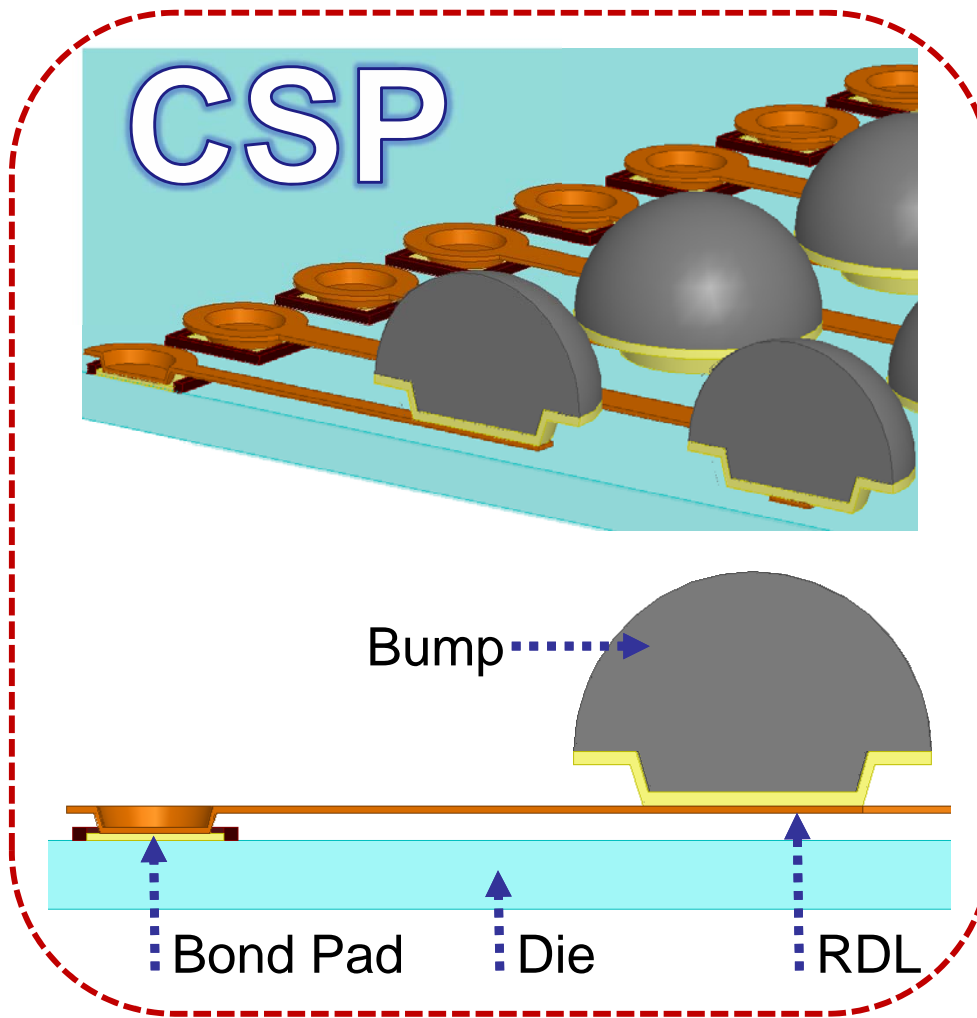


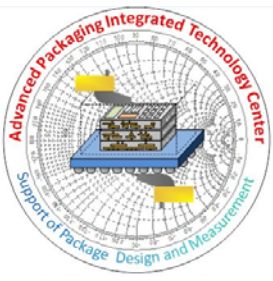
Introduction

NUK APITC

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- Purpose: 1. Max current rating of *RDL trace on CSP*.
2. Max current rating of *lead-frame of FC-QFN*.



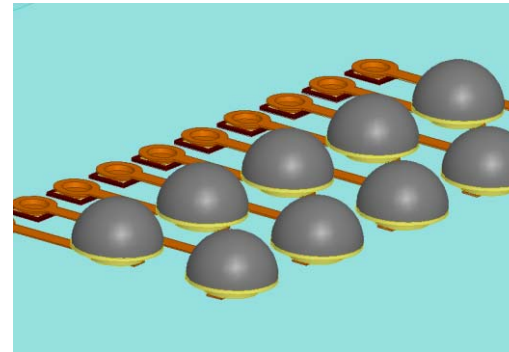


CSP Information

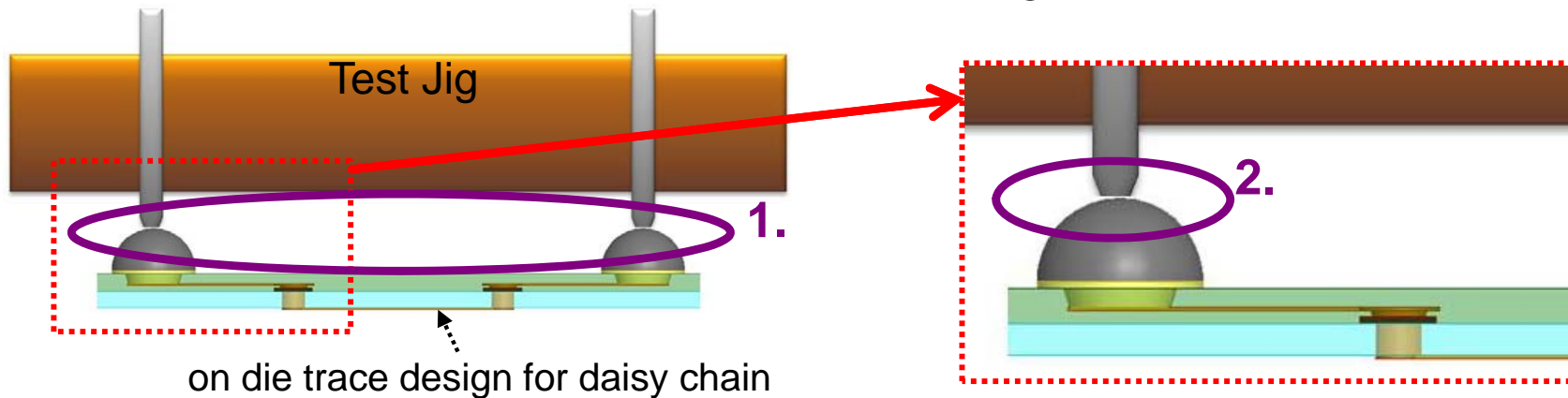
NUKAPITC

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- Die size: 5 x 5 mm²
- Die trace: W:10~50um
T : ?
- RDL trace: W/T ?

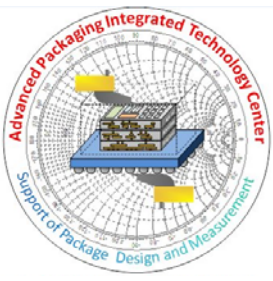


EV Board or Probe Card or Socket for Test Jig



Key point:

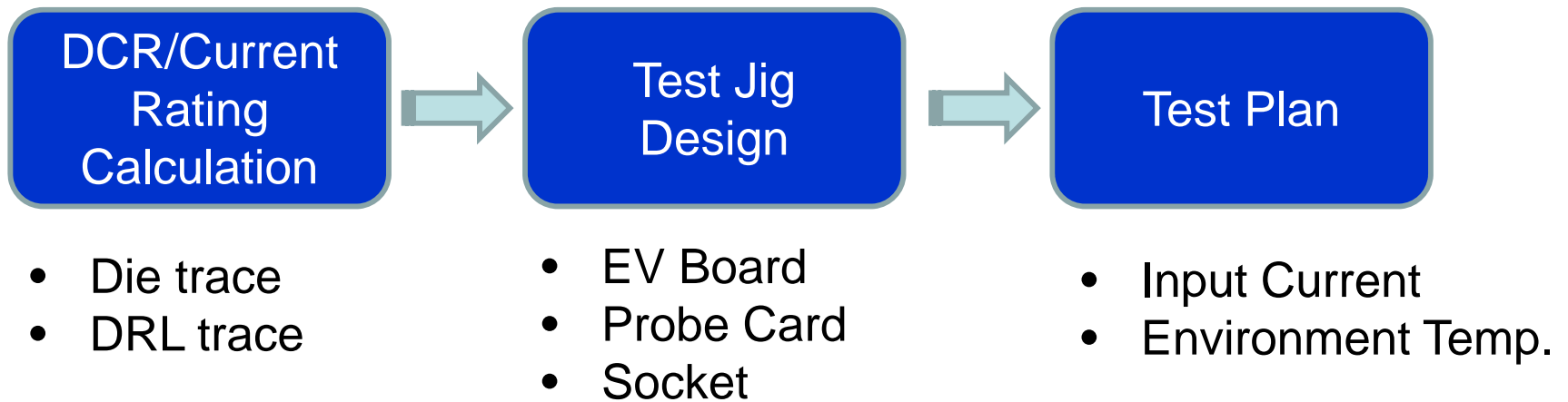
1. Is ball pitch a constant? No, different pitch jigs require.
2. The contact interface may not endure high current.

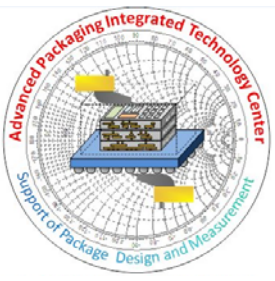


CSP DoE Flow

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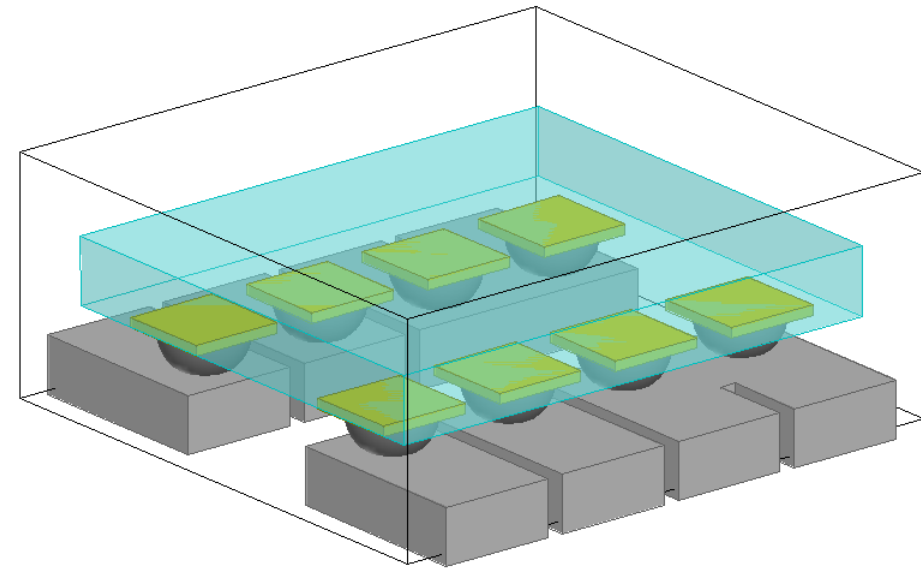
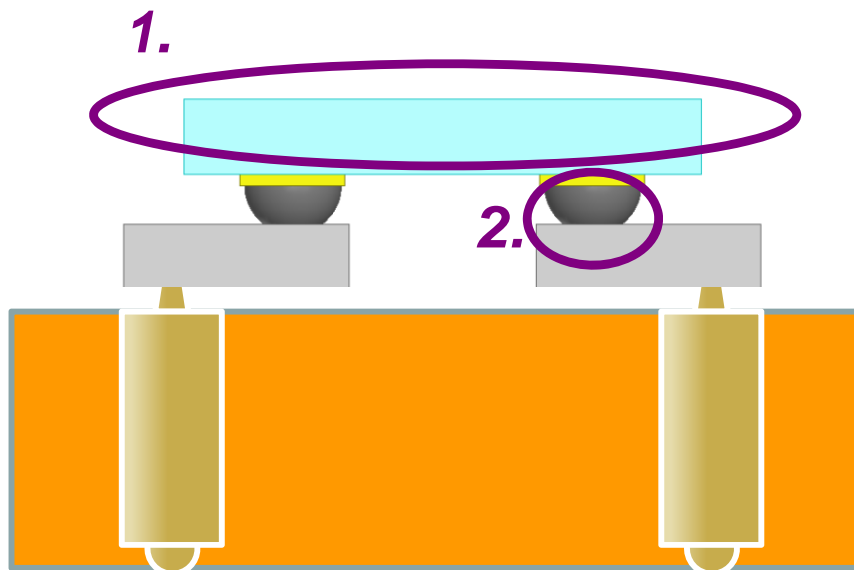


FC-QFN Information

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- Pitch: 0.4 mm
- L/F surface: Sn plating
- Die function: Analog SW



Key point:

1. SW die current rating.
2. The joint of solder bump may be a challenge.

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